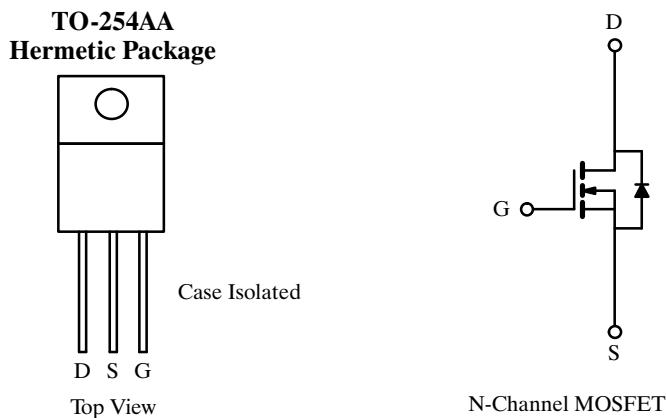


N-Channel Enhancement-Mode Transistors**Product Summary**

V _{DS} (V)	r _{D(on)} (Ω)	I _D (A)
500	0.515	12

Parametric limits in accordance with MIL-S-19500/592 where applicable.

**Absolute Maximum Ratings (T_C = 25°C Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	500	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current (T _J = 150°C)	I _D	12	A
T _C = 25°C		8	
Pulsed Drain Current	I _{DM}	48	
Avalanche Current	I _{AR}	12	
Maximum Power Dissipation	P _D	150	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Case	R _{thJC}	0.83	°C/W

TEMIC

2N7228JANTX/JANTXV

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Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = 1000 \mu\text{A}$	500			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}, T_J = -55^\circ\text{C}$			5.0	
		$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}, T_J = 25^\circ\text{C}$	2.0		4.0	
		$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}, T_J = 125^\circ\text{C}$	1.0			
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
		$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}, T_J = 125^\circ\text{C}$			± 200	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			25	μA
		$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	
		$V_{\text{DS}} = 500 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			1000	
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}, I_D = 12 \text{ A}$			0.515	Ω
		$V_{\text{GS}} = 10 \text{ V}, I_D = 8 \text{ A}, T_J = 125^\circ\text{C}$			0.9	
Dynamic						
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = 250 \text{ V}, V_{\text{GS}} = 10 \text{ V}, I_D = 12 \text{ A}$	55		120	nC
Gate-Source Charge ^c	Q_{gs}		5		19	
Gate-Drain Charge ^c	Q_{gd}		27		70	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 250 \text{ V}, R_L = 20.8 \Omega$ $I_D \approx 12 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 2.35 \Omega$			35	ns
Rise Time ^c	t_r				190	
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$				170	
Fall Time ^c	t_f				130	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				12	A
Pulsed Current	I_{SM}				48	
Diode Forward Voltage ^b	V_{SD}	$I_F = 12 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			1.7	V
Reverse Recovery Time	t_{rr}	$I_F = 12 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$			1600	ns

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.